EPIC Members - New Product Release November 2022



Advanced InP DFB Laser Sources for Silicon Photonics Hybrid Integration



About Us

UK-based design and manufacturing, located in Glasgow, Scotland

100mm wafer fab with capacity of 5,000 wafer starts per year (2000m² class 50 facility)

ISO 9001 Certification

20 year history designing and manufacturing III-V photonic devices

End-to-end chip solutions from design to volume manufacture

Over 80 staff and growing rapidly

Key strategic supplier to many Fortune 100 and Silicon Valley customers



Technology Expertise

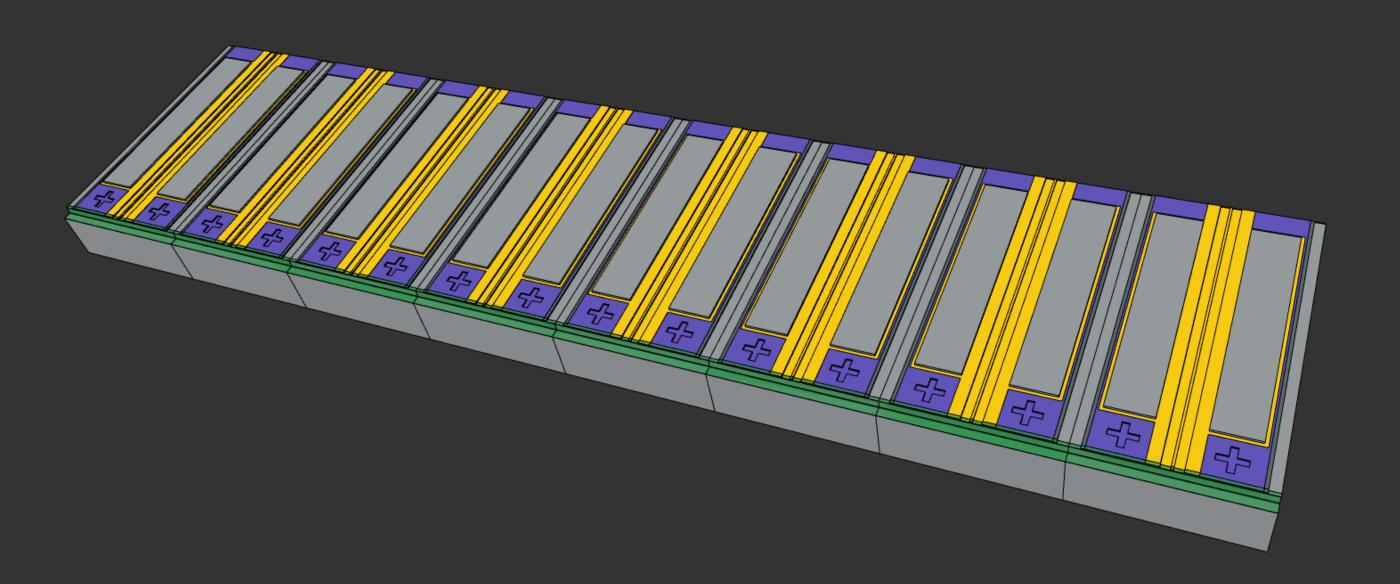
- Integrated design and manufacturing services for a broad range of photonic devices: FP & DFB lasers, SOAs, RSOAs, Detectors
- Key player in the SiPh ecosystem
- World class InP100 manufacturing platform
 - Multiple commercial users
- Established volume supplier shipping over 1 million lasers per month
- >45 million lasers in the field







InP100 DFB Lasers: Optimised for Si Photonic Integration



- Vertical alignment surfaces. +/- 5nm height accuracy to optical mode centre. (z-axis)
- Etched facets with self-aligned front-side fiducials to both ridge (x-axis) and facet (y-axis).
- Metal pads optimised for flip chip bonding.
 Optional AuSn solder.
- Back side alignment fiducials and chip IDs

Multi emitter arrays for integration with multiple Si input waveguides.

Sivers Photonics InP laser sources being integrated into all commercial SiPh Platforms





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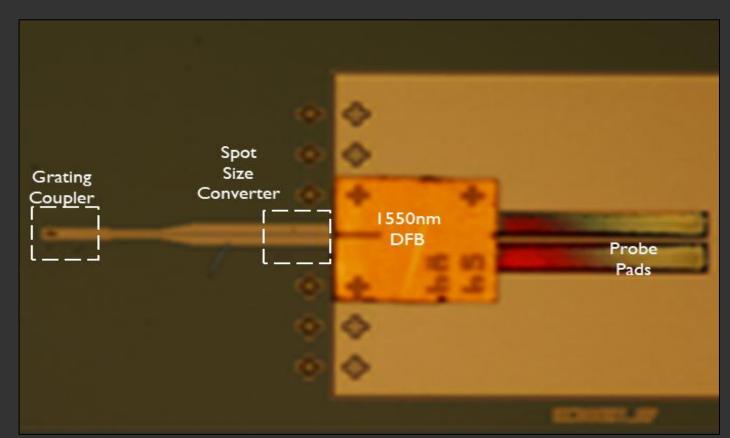
JDP Collaboration

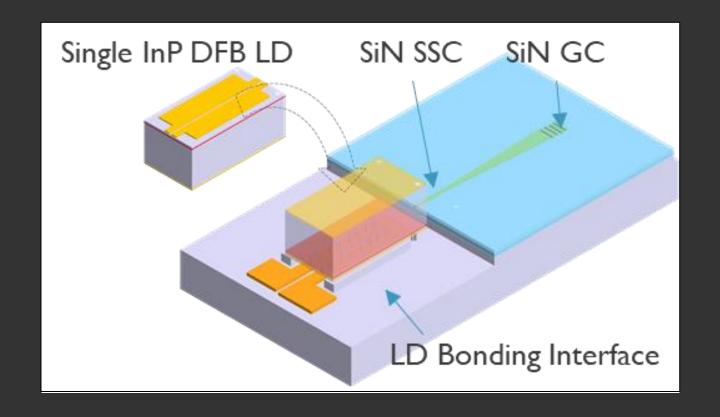
InP DFB lasers bonded onto imec Si/SiN Platform wafers

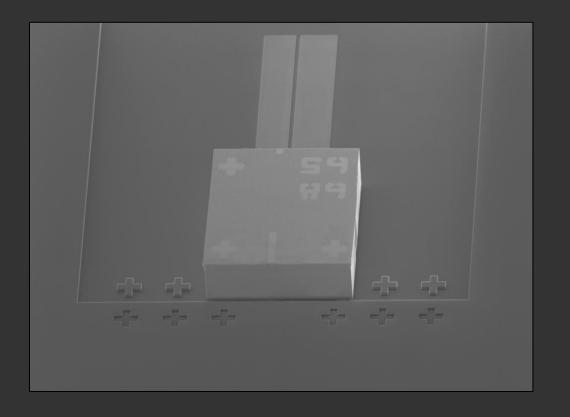
Initial results from first bonded devices:

- Single InP DFB lasers at wavelength ~1550nm
- Optical Power up to 40mW coupled into SiN waveguide
- High-Precision (≤0.3um) Laser Assisted FC Bonder Tool
- High mechanical stability with epoxy underfill process
- Coupling efficiency of 1.5±0.5 dB achieved
- FC-bonding of 4- and 8-channel O-band RSOA arrays (with 200GHz channel spacing) underway

More details available at the workshop on Heterogeneous Photonic Integrated Circuits (September 18, 9:00-12:30, room Shanghai)









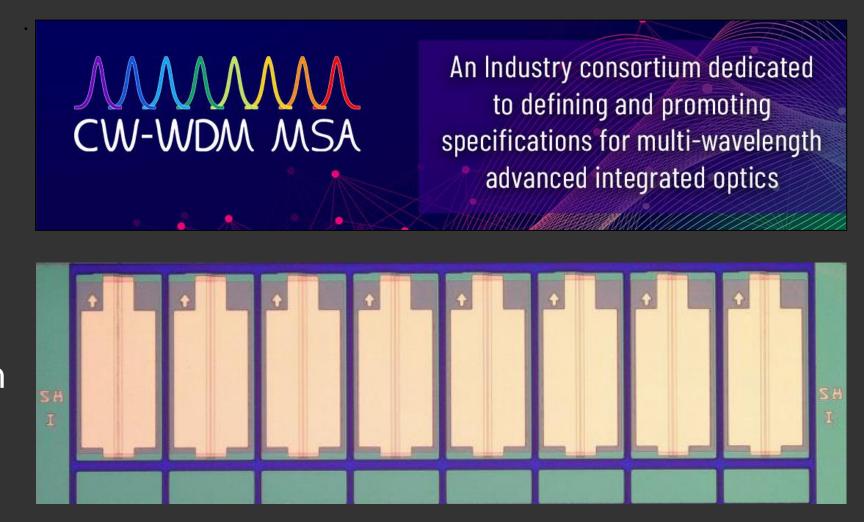


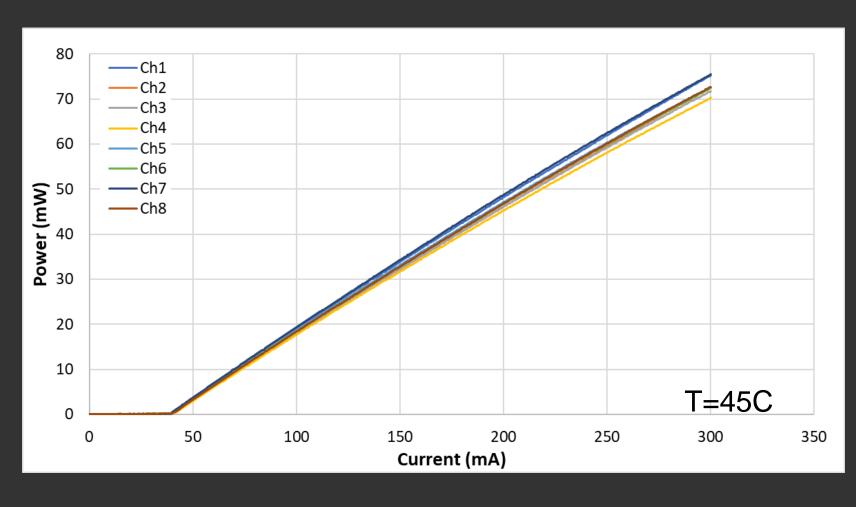
Custom DFB Laser Arrays for SiPh Applications

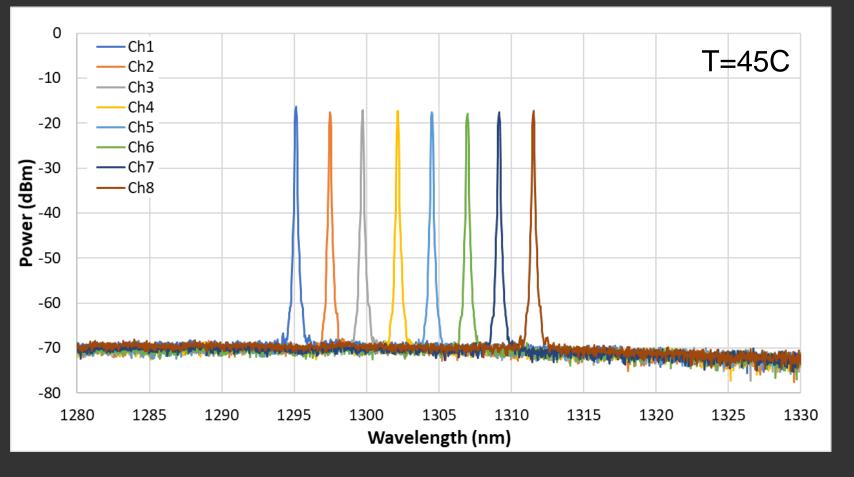
DFB laser diode arrays designed for use in CW-WDM MSA compliant applications

Key features

- > 50mW per channel CW operation
- 400GHz channel spacing around 1300nm
- Operating temp 20°C 70°C
- AllnGaAs MQW active region
- Proven high reliability GR468 qualification
- Suitable for non-hermetic applications







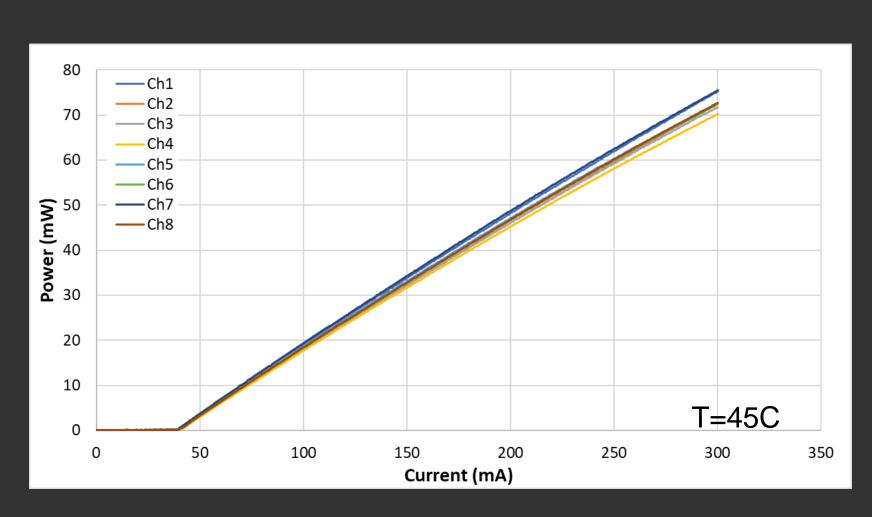




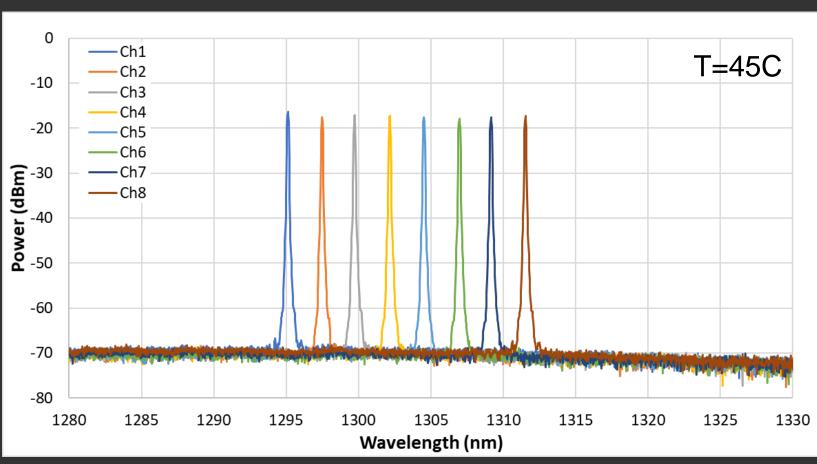
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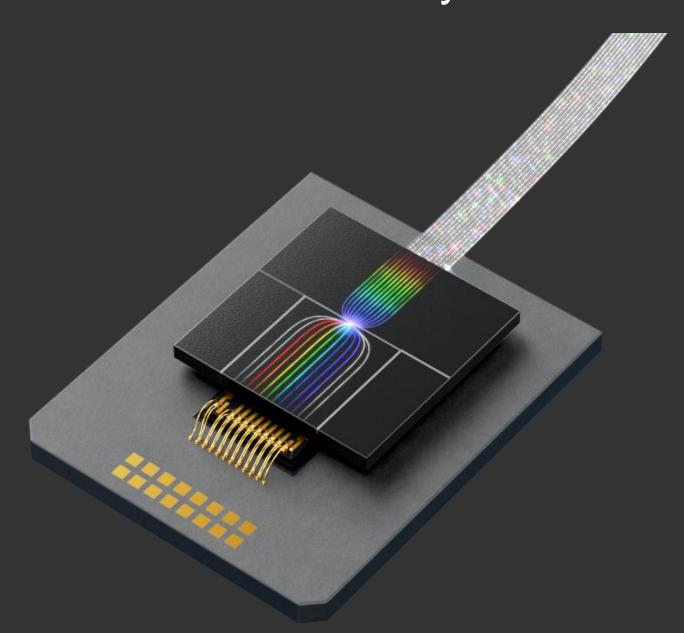








SuperNova™ Multi-Wavelength
Optical Source with Sivers
DFB Laser Arrays Inside



DEMONSTRATED LIVE AT ECOC 2022, SIVERS BOOTH #616





DFB laser diode arrays designed for use in CW-WDM MSA compliant applications. Demonstration of 32x arrays at 100GHz.



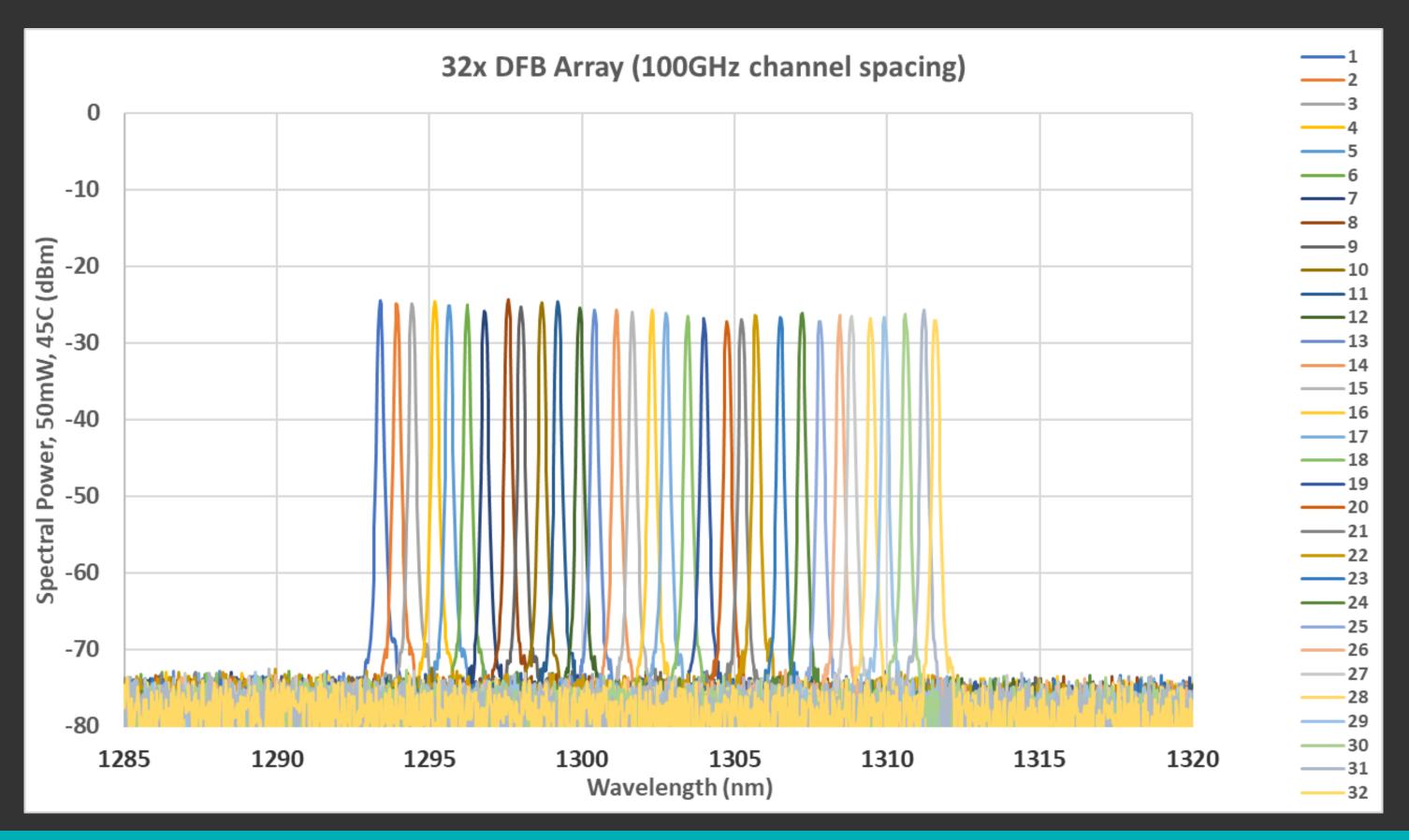






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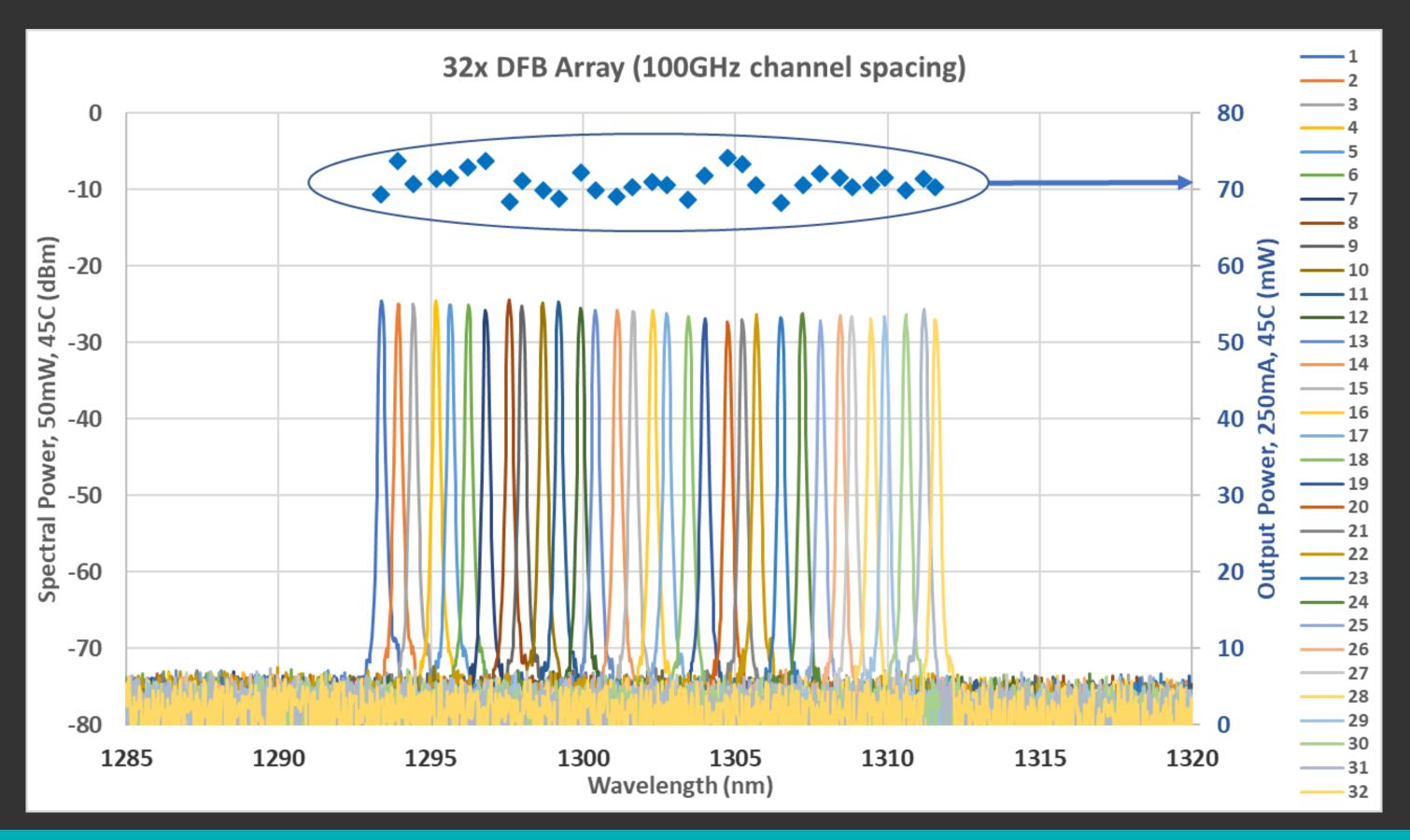






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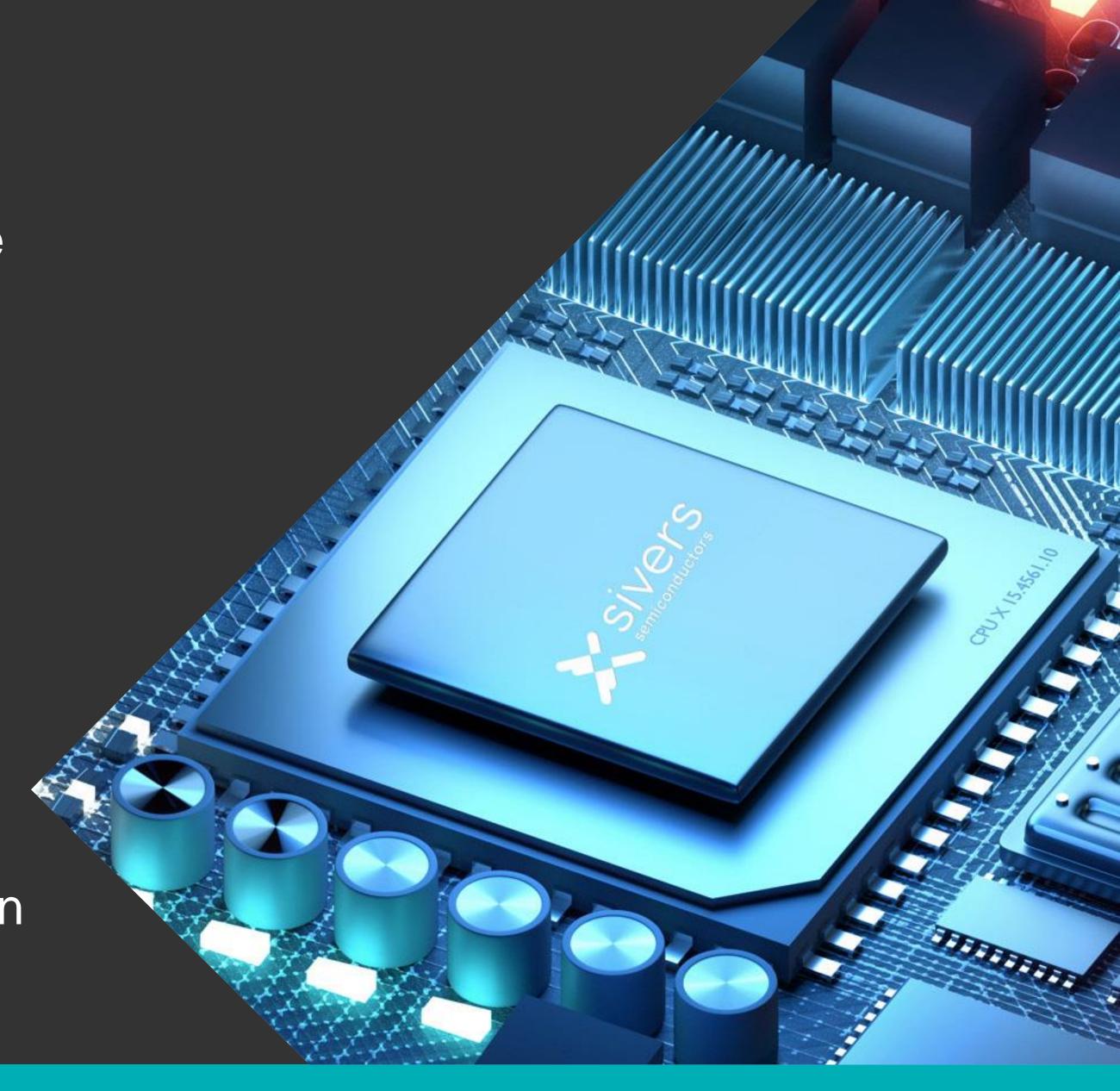


Summary

• Sivers Photonics has complete in-house capability for III-V chip design, fabrication, test, reliability and qualification

 Our InP100 platform provides advanced customised III-V devices for SiPh hybrid integration

 Sivers Photonics form a vital part of the SiPh ecosystem and are a key strategic supplier to many Fortune 100 and Silicon Valley customers.







Thank you

https://www.sivers-semiconductors.com/sivers-photonics/

